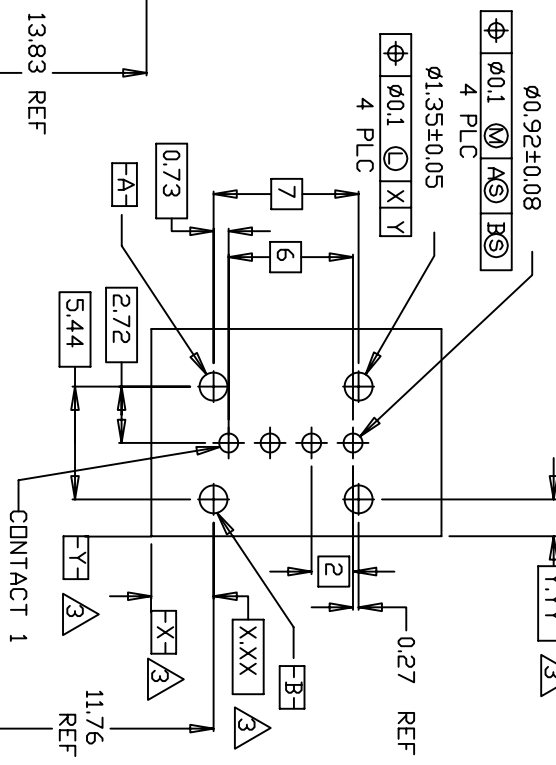
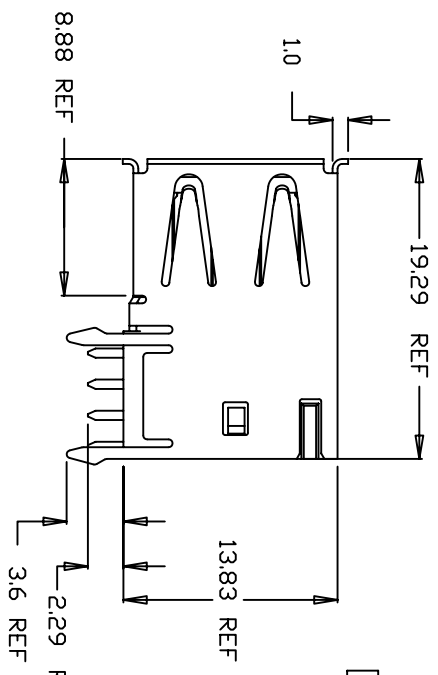
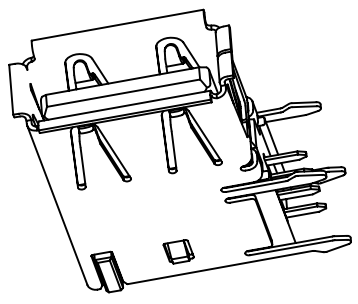
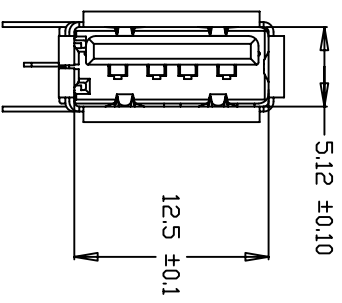
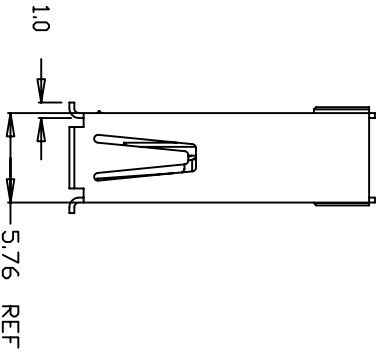


LOC	DIST	REV	DESCRIPTION	DATE	DWN	APVD
ES	00	P	LTR			
A			REVISED F B00-0215-04	16DEC04	G.Z. I.E.	

D



FRONT OF CONNECTOR

D

C

- 1 MATERIAL: PHOSPHOR BRONZE
- 2 CONTACTS - COPPER ALLOY

MATERIAL:
 CONTACTS - PHOSPHOR BRONZE
 SHELL - COPPER ALLOY

PLATING:
 CONTACTS - 0.076 μ m MINIMUM GOLD OVER 0.76 μ m MINIMUM PALLADIUM-NICKEL
 ON MATING AREA, 3.8 μ m MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27 μ m MINIMUM NICKEL
 SHELL 2~5 μ m MINIMUM BRIGHT TIN.
 CONTACT ALTERNATE PLATING: 0.76 μ m MINIMUM GOLD ON MATING AREA

DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PC BOARD THICKNESS DF 1.57±0.18

HOUSING - UL 94V-0 RATED THERMOPLASTIC, NATURAL

HOUSING - UL 94V-0 RATED THERMOPLASTIC, BLACK

C

B

A

- 3 RECOMMENDED PC BOARD THICKNESS DF 1.57±0.18
- 4 HOUSING - UL 94V-0 RATED THERMOPLASTIC, NATURAL
- 5 HOUSING - UL 94V-0 RATED THERMOPLASTIC, BLACK

A

DIMENSIONS		TOLERANCES UNLESS OTHERWISE SPECIFIED	
M/M			
0 PLC	±	±	
1 PLC	±	±0.13	
2 PLC	±	±	
3 PLC	±	±	
4 PLC	±	±	
4 ANGLES	±	±	

APPROVED	DATE	NAME	SCALE
OK	12MAR04	J. JIANG	NON
APPROVED	DATE	NAME	SCALE
OK	12MAR04	S. YAD	NON
APPROVED	DATE	NAME	SCALE
OK	12MAR04	T. SASAKI	NON

APPROVED	DATE	NAME	SCALE
OK	12MAR04	J. JIANG	NON

APPROVED	DATE	NAME	SCALE
OK	12MAR04	S. YAD	NON

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